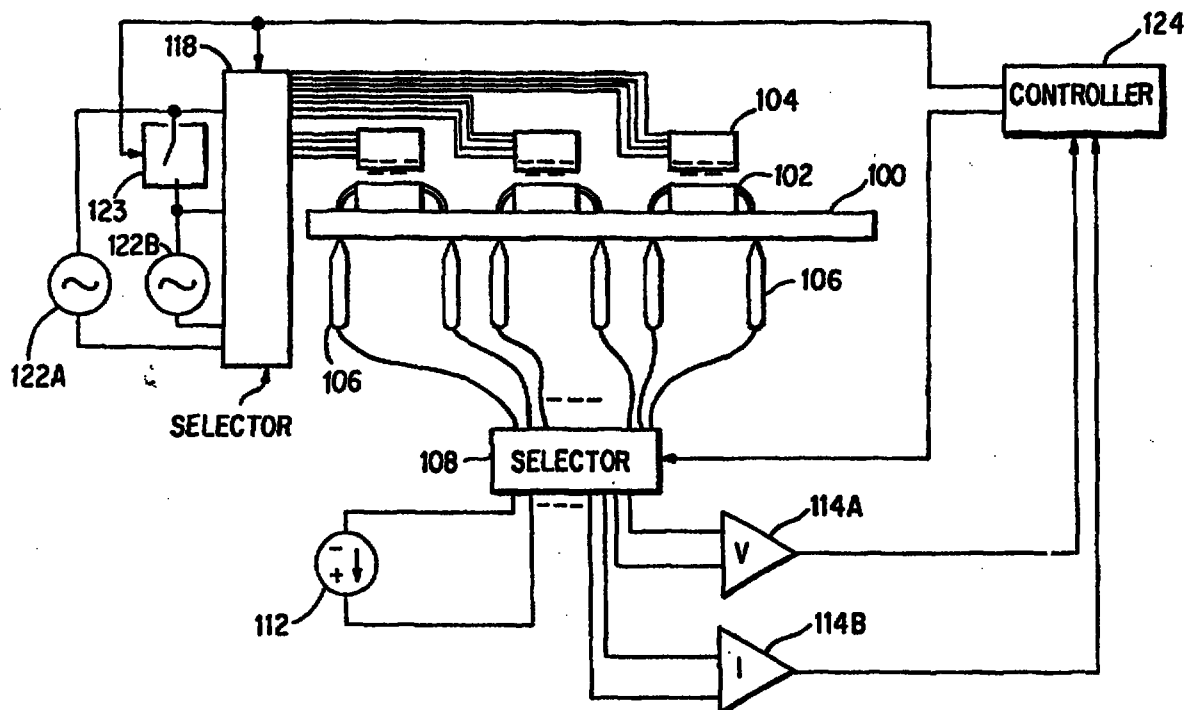


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(54) Title: MANUFACTURING DEFECT ANALYZER WITH IMPROVED FAULT COVERAGE



(57) Abstract

A manufacturing defect analyzer for printed circuit boards which can detect open circuit faults between leads of components and the printed circuit board. The manufacturing defect analyzer can operate in an inductive coupling mode or a capacitive coupling mode. The same sensors are used in each mode, allowing different leads on the same part to be tested using either technique. A method is also disclosed whereby the device is used to rapidly and accurately detect manufacturing defects.